SN54F86 ... J PACKAGE

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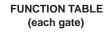
 Package Options Include Plastic Small-Outline (D) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

description

These devices contain four independent 2-input exclusive-OR gates. They perform the Boolean function $Y = A \oplus B$ or $Y = \overline{AB} + A\overline{B}$ in positive logic.

A common application is as a true/complement element. If one of the inputs is low, the other input is reproduced in true form at the output. If one of the inputs is high, the signal on the other input is reproduced inverted at the output.

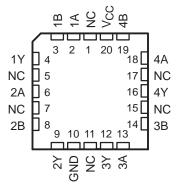
The SN54F86 is characterized for operation over the full military temperature range of -55° C to 125°C. The SN74F86 is characterized for operation from 0°C to 70°C.



INP	UTS	OUTPUT				
Α	В	Y				
L	L	L				
L	Н	н				
н	L	н				
н	Н	L				

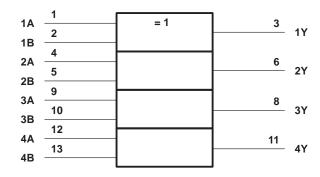
SN74F86 ... D OR N PACKAGE (TOP VIEW) 14 🛛 V_{CC} 1A 1B [4B 13 2 1Y Π 12 4A 3 2A [11 4Y 4 2В П 10 3B 5 2Y 6 9 3A 3Y GND 7 8

SN54F86 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

logic symbol[†]



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the D, J, and N packages.



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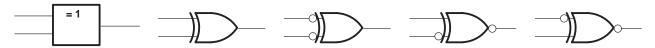
SN54F86, SN74F86 QUADRUPLE 2-INPUT EXCLUSIVE-OR GATES

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exclusive-OR logic

An exclusive-OR gate has many applications, some of which can be represented better by alternative logic symbols.

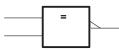
EXCLUSIVE OR

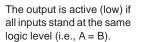


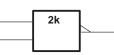
These are five equivalent exclusive-OR symbols valid for an 'F86 gate in positive logic; negation may be shown at any two ports.

LOGIC-IDENTITY ELEMENT

EVEN-PARITY ELEMENT

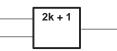






The output is active (low) if an even number of inputs (i.e., 0 or 2) are active.

ODD-PARITY ELEMENT



The output is active (high) if an odd number of outputs (i.e., only 1 of the 2) are active.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC}	–0.5 V to 7 V
Input voltage range, VI (see Note 1)	–1.2 V to 7 V
Input current range	–30 mA to 5 mA
Voltage range applied to any output in the high state	–0.5 V to V _{CC}
Current into any output in the low state	40 mA
Package thermal impedance, θ_{JA} (see Note 2): D package	127°C/W
N package	
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input voltage ratings may be exceeded provided the input current ratings are observed.
 - 2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions

		SN54F86			5	UNIT		
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.8			0.8	V
Iк	Input clamp current			-18			-18	mA
IOH	High-level output current			-1			-1	mA
IOL	Low-level output current			20			20	mA
ТА	Operating free-air temperature	-55		125	0		70	°C



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS			SN54F86		5	UNIT		
PARAMETER	IE	TEST CONDITIONS			MAX	MIN	TYP†	MAX	UNIT
VIK	V _{CC} = 4.5 V,	lj = -18 mA			-1.2			-1.2	V
Vou	V _{CC} = 4.5 V,	I _{OH} = -1 mA	2.5	3.4		2.5	3.4		V
VOH	V _{CC} = 4.75 V,	I _{OH} = -1 mA				2.7			v
V _{OL}	V _{CC} = 4.5 V,	I _{OL} = 20 mA		0.3	0.5		0.3	0.5	V
lj	V _{CC} = 5.5 V,	V _I = 7 V			0.1			0.1	mA
ΙIΗ	V _{CC} = 5.5 V,	VI = 2.7 V			20			20	μA
١ _{١L}	V _{CC} = 5.5 V,	V _I = 0.5 V			- 0.6			- 0.6	mA
los‡	V _{CC} = 5.5 V,	$V_{O} = 0$	-60		-150	-60		-150	mA
ІССН	V _{CC} = 5.5 V,	See Note 3		15	23		15	23	mA
ICCL	V _{CC} = 5.5 V,	V _I = 4.5 V		18	28		18	28	mA

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

[‡]Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second. NOTE 3: I_{CCH} is measured with outputs open, and the A or B input (not both) at 4.5 V. Remaining inputs are grounded.

switching characteristics (see Figure 1)

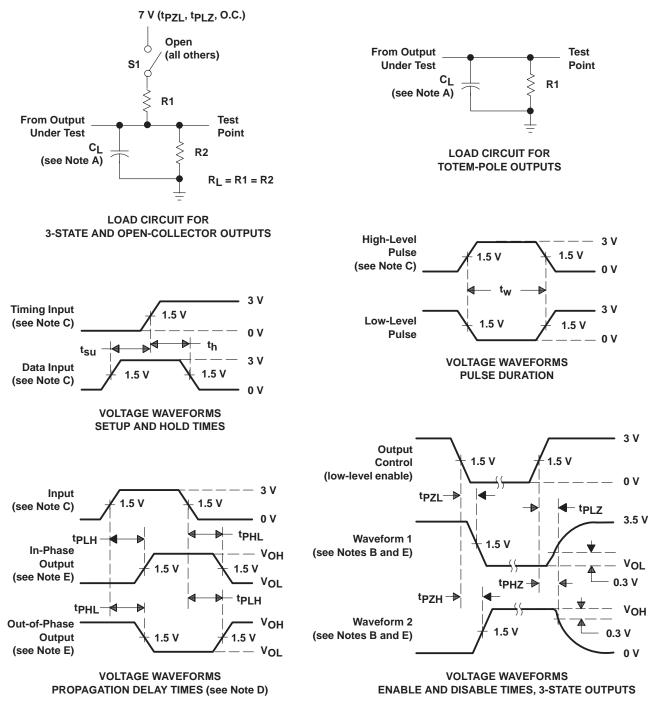
PARAMETER	FROM (INPUT)	TO (OUTPUT)	C _I RI	CC = 5 V = 50 p = 500 9 = 25°C 7F86	F, Ω,	CL RL	= 50 pF = 500Ω = MIN t			UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
^t PLH	A or B (other input low)	V	3	4	5.5	3	7	3	6.5	
^t PHL		Ť	3	4.2	5.5	2.6	8	3	6.5	ns
^t PLH	A or B	A or B	3.5	5.3	7	3.5	10	3.5	8	ns
^t PHL	(other input high)		3	4.7	6.5	3	8	3	7.5	115

§ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



SN54F86, SN74F86 QUADRUPLE 2-INPUT EXCLUSIVE-OR GATES

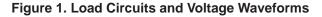
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PARAMETER MEASUREMENT INFORMATION

NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
- Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: $PRR \le 1$ MHz, $t_r = t_f \le 2.5$ ns, duty cycle = 50%.
- D. When measuring propagation delay times of 3-state outputs, switch S1 is open.
- E. The outputs are measured one at a time with one transition per measurement.





PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Packag Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74F86D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74F86DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74F86DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74F86DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74F86DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74F86DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74F86N	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74F86NE4	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74F86NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74F86NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74F86NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. TBD: The Pb-Free/Green conversion plan has not been defined.

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at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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PACKAGE OPTION ADDENDUM

18-Sep-2008

to Customer on an annual basis.

TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*Al	dimensions are nominal												
	Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
	SN74F86DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
	SN74F86NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1



PACKAGE MATERIALS INFORMATION

11-Mar-2008



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74F86DR	SOIC	D	14	2500	346.0	346.0	33.0
SN74F86NSR	SO	NS	14	2000	346.0	346.0	33.0

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